

System Specifications		SE600	SE600-X
Panel Size Capacity (Max)	510 x 510 mm (20.0 x 20.0 in.)		710 x 610 mm (28.0 x 24.0 in.)
Panel Size Capacity (Min)	50 x 50 mm (2.0 x 2.0 in.)		100 x 100 mm (4.0 x 4.0 in.)
System Dimensions (W x D x H)	110 x 127 x 139 cm		133 x 155 x 139 cm
Weight	≈ 965 kg (2127 lbs.)		≈ 1239 kg (2731 lbs.)
Maximum Panel Weight	3.0 kg (6.6 lbs)		10.0 kg (22 lbs)
Board Thickness	0.3 mm to 5.0 mm (0.01 in. to 0.2 in.)		0.5 mm to 6.0 mm (0.02 in. to 0.24 in.)
Board edge clearance (Top)	Top: 2.5 mm (0.10 in.); Bottom: 3.0 mm (0.12 in.)		
Component Clearance (Top)	Top (above belt): 20.1 mm (0.78 in.); Bottom: 25.4 mm (1.0 in.)		
Conveyor Speed Range	150 - 450 mm/sec (5.9 - 17.7 in./sec)		
Conveyor Adjustment	Automatic		
Functional Specifications			
Maximum Inspection Area	508 x 503 mm (20.0 x 19.5 in.)		708 x 603 mm (27.5 x 23.5 in.)
Field-of-View (FOV)	32 x 32 mm (1.26 x 1.26 in.)		
X and Y Pixel Size @	High Resolution: 15 μm (0.6 mils); High Speed: 30 μm (1.2 mils)		
Paste Height Range	50 - 500 μm (2 - 20 mils)		
Height Resolution	0.2 μm (0.008 mils)		
Maximum Board Warp	< 2% of PCB diagonals or max. of 6.35mm (0.25 in) total		
Maximum Pad Size in FOV	15 x 15 mm (0.6 x 0.6 in.)		
Measurement Types	Height, Area, Volume, Registration, Bridge Detection, Defect Review		
Machine Interface	SMEMA, RS232 & Ethernet		
Power Requirements	100 - 130 / 220 - 240V (10%), 50/60 Hz, 10 - 15 amps		
Compressed Air Requirements	5.6 to 7.0 Kg/cm² (80 to 100 psi @ 4 cfm)		
Performance Specifications			
Inspection Speed @ 30um	108 cm²/sec peak (80 cm²/sec avg)		
Inspection Speed @ 15um	56 cm²/sec peak (30 cm²/sec avg)		
Fiducial, Barcode and Skip Mark	All-in-one scan		
Height Accuracy †	2 μm on a Certification Target		
Gage R&R †	<<5%, 6 σ on Printed Circuit Board; <<2% 6 σ on Certification Target		
† Under controlled conditions			
Options			
SPC software, Barcode Readers (1D/2D), Programming Software: ePM-SPI/AOI & GC-PowerPlace, Offline Defect Review, Certification Target			

SE600™ 3D SPI

Ultimate Precision Accuracy with World-class Usability



Contact CyberOptics today for more information
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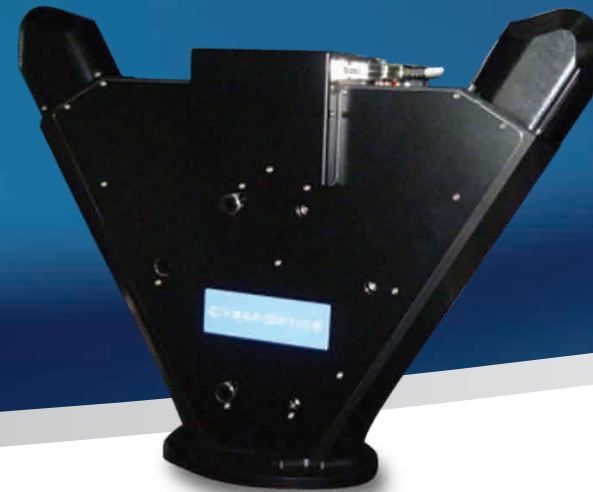


SE600™ True Measurement, Supreme Quality

Performance at its Best (Accuracy and GR&R)

SE600™ comes with a standard dual illumination sensor designed and built exclusively by CyberOptics. The sensor offers the best repeatability and reproducibility results - even on the smallest paste deposits. The sensor is manufactured as an integrated assembly with absolutely no moving parts - which means no machine-to-machine variation. So, you can be assured that there is no drift time, no parts to wear and most importantly - no recalibration required.

The SE600-X™ supports large board capability of up to 710 x 610mm, inspecting the most demanding assemblies without compromising measurement accuracy and repeatability.



Dual Illumination Sensor

Award-Winning Intuitive Software

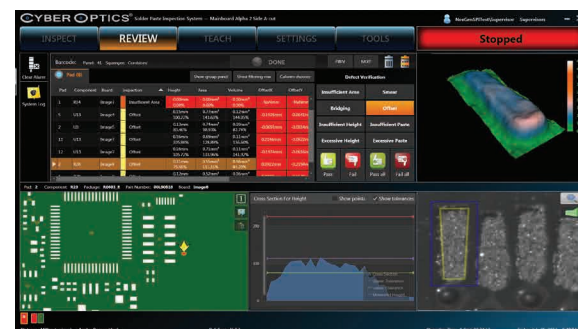


SPI SOFTWARE

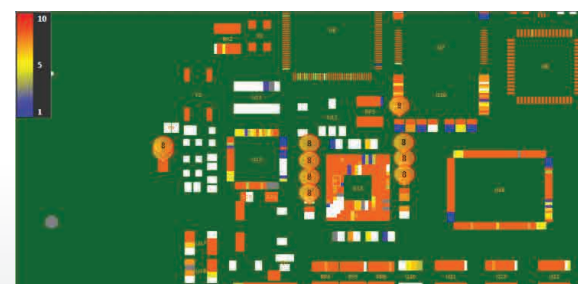
The brand-new V5 series software delivers world-class user experience with its intuitive interface, completely changing the way users interact with our system. Yet, at the same time, the software is extremely stable and simple to use enabling shortest learning curve.

With full multi-touch experience, SPI V5 series software offers a range of revolutionary features that enable smarter and faster inspection:

- Seamless integration of all applications - Teach, Inspection, Defect Review and Real-time SPC
- Unlimited undo-redo and global search options in Teach
- Loads of smart, informative and relevant charts that provide yield summary, FPY information, hotspot display, top 10 pad failures, historical panel and more
- Easy, hassle-free operation using multi touch, multi-selection, pinch-zoom, and pan-move options



Defect Review Interface



Hot Spot Display



Real-time SPC

Feedback, Feed Forward Ready

SE600™ fully supports feedback and feed forward capability with leading Solder Paste Printer and SMT Mounter vendors respectively. With simple configuration settings, SE600™ gives you the power to do more with SPI results - optimize printing process, establish stencil cleaning cycles and fine-tune printer setup. All this means reduced rework costs, increased production throughput and improved yields.

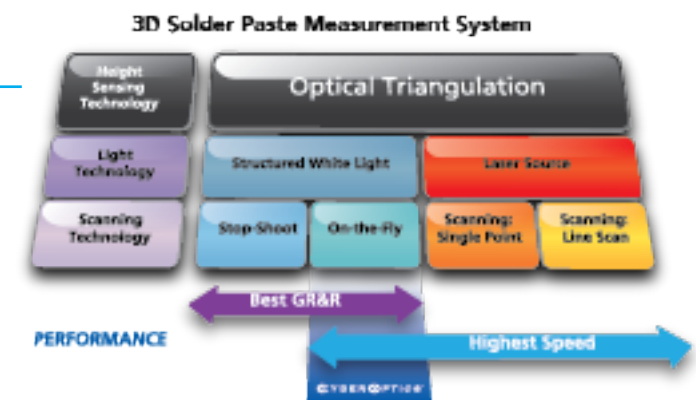


All Major Screen Printers

CyberOptics

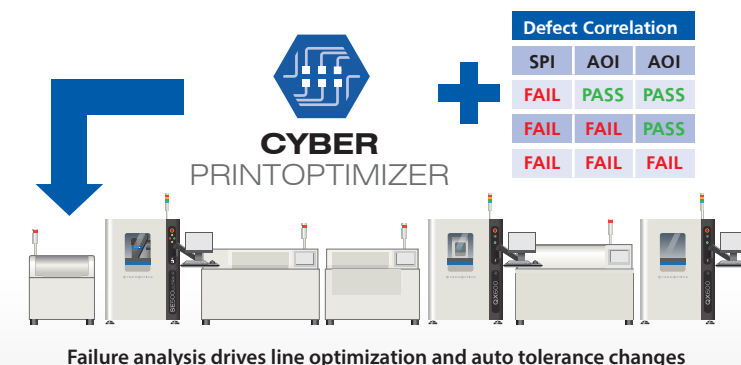
High Speed, On-The-Fly Inspection

SE600™ incorporates CyberOptics' patented 3D sensing technology that uses white strobe light acquiring full FOVs with each strobe and minimizing vibration effects - delivering good accuracy and consistent repeatability. You can measure ANY PCB surface - including flexible circuits - as white light causes minimum diffusion. With its continuous image acquisition, you can be assured of fast, focused and reliable inspection.



CyberPrint OPTIMIZER™ Ready

CyberPrint OPTIMIZER™ automatically optimizes the print process by proactively analyzing accurate trend data - first-ever in the industry! Pre-defined templates help you get started quickly while customizable rules support perfect customization for specific product needs. CyberPrint OPTIMIZER™'s predictive process improvement gets you better yields and reduces downtime.



Fast, Scalable SPC Solution

CyberReport™ offers full-fledged machine-level to factory-level SPC capability with powerful historical analysis and reporting tools.

